

# RELEASE FILM RLX25

RLX25 – Release Film is a very economical solution to be used in all different types of lamination processes. The maximum laminating temperature is 190°C.

RLX25– Release Film is an inert material and leaves no residues on the PCB - surfaces and shows brilliant dimensional

behaviour under thermal pressure and guarantees a very easy release function.

## PROPERTIES

Thermal usage in the hot press	max. 190 °C (374 °F) for 90min.	
Melting point	260 °C ± 10 °C	
Density	1.400 gcm <sup>-3</sup>	ASTM-D1505
Tensile strength	MD ≥ 200 Nmm <sup>-2</sup> TD ≥ 220 Nmm <sup>-2</sup>	ASTM D882A ASTM D882A
Elongation at break (v= 50mm/min <sup>-1</sup> )	MD ≥ 125 % TD ≥ 100 %	ASTM D882A ASTM D882A
Heat shrinkage (150°C / 30min.)	MD ≤ 3,7 % TD ≤ 1,5 %	ASTM D1204 ASTM D1204
Coefficient of friction (static) Coefficient of friction (dynamic)	0.28 0.15	ASTM D1894 ASTM D1894
Decomposition temperature	> 280 °C	
Moisture absorption	< 0.9 % at common room conditions	
Appearance	Transparent	
Haze	2,2 %	ASTM-D1003
Surface	Smooth - both sides, Ra < 0.3 µm	
Storage Life	> 1 year at room temperature	
Thickness	25 µm – 1.0 mm	
Length of film	1000 m	
Roll widths	660, 680, 991, 1295 mm	

Subject to changes due to technical improvements without prior notice.

Other dimensions on request.